

Tender of

RMB-denominated 2.20 per cent. Bonds due 2026 (the “Additional 2026 Bonds”) (to be consolidated and form a single series with the RMB9 billion 2.20 per cent. Bonds due 2026 (the “Original 2026 Bonds”))

RMB-denominated 2.28 per cent. Bonds due 2027 (the “Additional 2027 Bonds”) (to be consolidated and form a single series with the RMB9 billion 2.28 per cent. Bonds due 2027 (the “Original 2027 Bonds”))

and

RMB-denominated 2.45 per cent. Bonds due 2034 (the “Additional 2034 Bonds”) (to be consolidated and form a single series with the RMB5 billion 2.45 per cent. Bonds due 2034 (the “Original 2034 Bonds”))

(together, the “Additional Bonds”)

To be held on 14 August 2024

The Ministry of Finance of the People’s Republic of China (the “Ministry of Finance”) announces that a tender of the Additional 2026 Bonds, the Additional 2027 Bonds and the Additional 2034 Bonds of the Central People’s Government will be held on Wednesday, 14 August 2024, for settlement on Friday, 16 August 2024.

A total of RMB3 billion Additional 2026 Bonds, a total of RMB3 billion Additional 2027 Bonds and a total of RMB3 billion Additional 2034 Bonds will be made available for competitive tender on a price-bid basis by any qualified Central Moneymarkets Unit (“CMU”) members through the CMU BID. Upon issuance, the Additional 2026 Bonds will be consolidated and form a single series with the Original 2026 Bonds (the “2026 Bonds”), the Additional 2027 Bonds will be consolidated and form a single series with the Original 2027 Bonds (the “2027 Bonds”) and the Additional 2034 Bonds will be consolidated and form a single series with the Original 2034 Bonds (the “2034 Bonds”, together with the 2026 Bonds and the 2027 Bonds, the “Bonds”). The 2026 Bonds, the 2027 Bonds and the 2034 Bonds bear interest at 2.20 per cent. per annum, 2.28 per cent. per annum and 2.45 per cent. per annum respectively. The 2026 Bonds, the 2027 Bonds and the 2034 Bonds will mature in 2026, 2027 and 2034 respectively, on the last interest payment date of the relevant series of Bonds. Each series of the Additional Bonds will be issued at the uniform issue price i.e. the lowest accepted price of the successful competitive tender bids for the relevant series, plus accrued interest.

Each tender must be for an amount of RMB500,000 or integral multiples thereof and the difference between any specified tender prices, should be at least 0.01%, rounded to two decimal places.

The tender results will be published on the website of the Hong Kong Monetary Authority (“HKMA”) (<https://www.hkma.gov.hk>) and the CMU Website (<https://www.cmu.org.hk>).

The Tender Information Memorandum of the Ministry of Finance dated 8 August 2024 includes the details of the tender of the Additional Bonds, including the terms of the Additional Bonds, the tender arrangements and the application, payment and settlement procedures. Copies of the Tender Information Memorandum can be obtained from the HKMA at 55/F, Two International Finance Centre, 8 Finance Street, Central, Hong Kong (Tel: 8100 0136) or from the Issuing and Lodging Agent, Bank of Communications Co., Ltd, Hong Kong Branch at 20 Pedder Street, Central, Hong Kong (Tel: 2315 7386

/ 2315 7387). It can also be downloaded from the respective websites of the HKMA and the Issuing and Lodging Agent at <https://www.bankcomm.com.hk>.

The Ministry of Finance will tender the Additional Bonds through the CMU BID. The tender and settlement of the Additional Bonds will be governed by the Tender Information Memorandum and the Applicable Terms and Conditions of CMU BID issued by the HKMA as the system administrator and service provider of the CMU BID, as amended from time to time, the CMU Operating Procedures and other relevant CMU rules (subject to any amendments under the Tender Information Memorandum).

The Ministry of Finance has appointed Bank of Communications Co., Ltd. Hong Kong Branch as the Issuing and Lodging Agent to administer the tender of the Additional Bonds on its behalf.

The Ministry of Finance of the People's Republic of China

8 August 2024

Bonds Tender Information

Information of each series of the Additional Bonds:

CMU Instrument No.	:	2026 Bonds: BCMKFB24001 2027 Bonds: BCMKFB24002 2034 Bonds: BCMKFB24004
Tender Date and Time	:	Wednesday, 14 August 2024 9:30 a.m. to 10:30 a.m.
Issue and Settlement Date	:	Friday, 16 August 2024
Aggregate Principal Amount Tendered	:	Additional 2026 Bonds: RMB3 billion Additional 2027 Bonds: RMB3 billion Additional 2034 Bonds: RMB3 billion
Denomination	:	RMB500,000 each
Issue Price	:	Additional Bonds will be issued at the lowest accepted price of the successful competitive tender bids, plus accrued interest
Maturity Date	:	Last interest payment date of the relevant series of Bonds in 2026, 2027 and 2034, respectively
Interest Rates and Accrued Interest (if applicable)	:	2026 Bonds: 2026 Bonds bear interest at 2.20 per cent. per annum and the accrued interest on each 2026 Bond from and including 15 March 2024 up to but excluding 16 August 2024 is RMB4,641.10 2027 Bonds: 2027 Bonds bear interest at 2.28 per cent. per annum and the accrued interest on each 2027 Bond from and including 15 March 2024 up to but excluding 16 August 2024 is RMB4,809.86 2034 Bonds: 2034 Bonds bear interest at 2.45 per cent. per annum and the accrued interest on each 2034 Bond from and including 15 March 2024 up to but excluding 16 August 2024 is RMB5,168.49
Interest Payment Dates	:	15 March and 15 September in each year, subject to the modified following business day convention
Tender Amount	:	RMB500,000 or integral multiples thereof and the difference between any specified tender prices should be at least 0.01%, rounded to two decimal places
Other details	:	Please refer to the Tender Information Memorandum

The Ministry of Finance of the People's Republic of China

8 August 2024

Note: This Tender Notice is published in Chinese and English. The English version is intended for ease of reference only. In the event of any inconsistency between the Chinese version and English version of this Tender Notice, the Chinese version shall prevail.